

Distributed by:

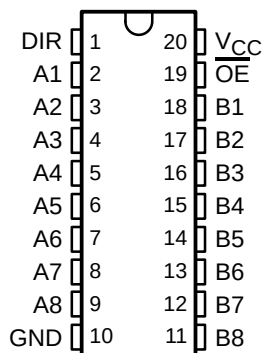


www.Jameco.com ♦ 1-800-831-4242

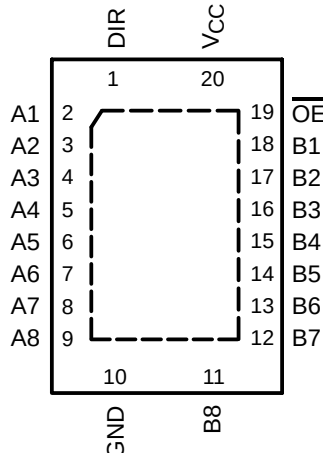
The content and copyrights of the attached
material are the property of its owner.

- Typical V_{OLP} (Output Ground Bounce) <1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

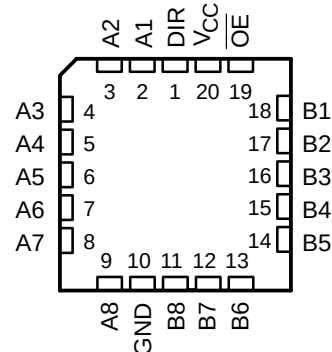
SN54ABT245A ... J OR W PACKAGE
SN74ABT245B ... DB, DGV, DW, N, NS,
OR PW PACKAGE
(TOP VIEW)



SN74ABT245B ... RGY PACKAGE
(TOP VIEW)



SN54ABT245B ... FK PACKAGE
(TOP VIEW)



description/ordering information

These octal bus transceivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so the buses are effectively isolated.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74ABT245BN	SN74ABT245BN
	QFN – RGY	Tape and reel	SN74ABT245BRGYR	AB245B
	SOIC – DW	Tube	SN74ABT245BDW	ABT245B
		Tape and reel	SN74ABT245BDWR	
	SOP – NS	Tape and reel	SN74ABT245BNSR	ABT245B
	SSOP – DB	Tape and reel	SN74ABT245BDBR	AB245B
	TSSOP – PW	Tape and reel	SN74ABT245BPWR	AB245B
	TVSOP – DGV	Tape and reel	SN74ABT245BDGVR	AB245B
–55°C to 125°C	VFBGA – GQN	Tape and reel	SN74ABT245BGQNR	AB245B
	CDIP – J	Tube	SNJ54ABT245AJ	SNJ54ABT245AJ
	CFP – W	Tube	SNJ54ABT245AW	SNJ54ABT245AW
	LCCC – FK	Tube	SNJ54ABT245AFK	SNJ54ABT245AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

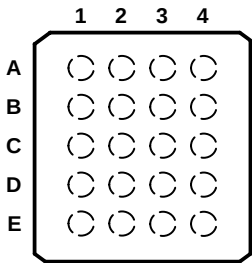
Copyright © 2002, Texas Instruments Incorporated
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

description/ordering information (continued)

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

SN74ABT245B . . . GQN PACKAGE
(TOP VIEW)



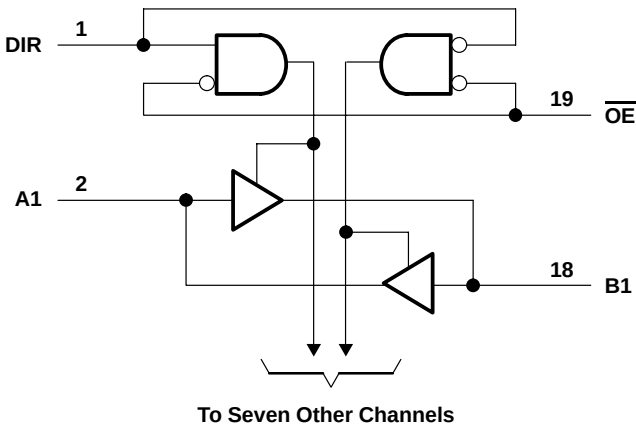
terminal assignments

	1	2	3	4
A	A1	DIR	V_{CC}	$\overline{OE}$
B	A3	B2	A2	B1
C	A5	A4	B4	B3
D	A7	B6	A6	B5
E	GND	A8	B8	B7

FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic diagram (positive logic)



Pin numbers shown are for the DB, DGV, DW, FK, J, N, NS, PW, RGY, and W packages.

SN54ABT245A, SN74ABT245B OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS081J – JANUARY 1991 – REVISED NOVEMBER 2002

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABT245A	96 mA
SN74ABT245B	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	70°C/W
(see Note 2): DGV package	92°C/W
(see Note 2): DW package	58°C/W
(see Note 2): GQN package	78°C/W
(see Note 2): N package	69°C/W
(see Note 2): NS package	60°C/W
(see Note 2): PW package	83°C/W
(see Note 3): RGY package	37°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.
3. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 4)

		SN54ABT245A		SN74ABT245B		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		5		5	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate			200		μs/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN54ABT245A, SN74ABT245B

OCTAL BUS TRANSCEIVERS

WITH 3-STATE OUTPUTS

SCBS081J – JANUARY 1991 – REVISED NOVEMBER 2002

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T _A = 25°C			SN54ABT245A		SN74ABT245B		UNIT
			MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	
V _{IK}		V _{CC} = 4.5 V, I _I = -18 mA			-1.2		-1.2		-1.2	V
V _{OH}		V _{CC} = 4.5 V, I _{OH} = -3 mA		2.5		2.5		2.5		V
		V _{CC} = 5 V, I _{OH} = -3 mA		3		3		3		
		V _{CC} = 4.5 V		2		2				
				2*				2		
V _{OL}		V _{CC} = 4.5 V			0.55		0.55			V
					0.55*				0.55	
V _{hys}				100						mV
I _I	Control inputs	V _{CC} = 0 to 5.5 V, V _I = V _{CC} or GND			±1		±1		±1	μA
	A or B ports	V _{CC} = 2.1 V to 5.5 V, V _I = V _{CC} or GND			±20		±100		±20	
I _{OZPU}		V _{CC} = 0 to 2.1 V, V _O = 0.5 V to 2.7 V, $\overline{OE}$ = X			±50		±50		±50	μA
I _{OZPD}		V _{CC} = 2.1 V to 0, V _O = 0.5 V to 2.7 V, $\overline{OE}$ = X			±50		±50		±50	μA
I _{OZH} [‡]		V _{CC} = 2.1 V to 5.5 V, V _O = 2.7 V, $\overline{OE}$ ≥ 2 V			10		10		10	μA
I _{OZL} [‡]		V _{CC} = 2.1 V to 5.5 V, V _O = 0.5 V, $\overline{OE}$ ≥ 2 V			-10		-10		-10	μA
I _{off}		V _{CC} = 0, V _I or V _O ≤ 4.5 V			±100				±100	μA
I _{CEX}		V _{CC} = 5.5 V, V _O = 5.5 V			50		50		50	μA
I _O [§]		V _{CC} = 5.5 V, V _O = 2.5 V	-50	-140	-180	-50	-180	-50	-180	mA
I _{CC}	A or B ports	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND			5	250	250	250	250	μA
					22	30	30	30	30	mA
					1	250	250	250	250	μA
ΔI _{CC} [¶]	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			1.5		1.5		1.5	mA
					50		50		50	μA
	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND			1.5		1.5		1.5	mA
C _i	Control inputs	V _I = 2.5 V or 0.5 V			4					pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			8					pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN54ABT245A, SN74ABT245B OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS081J – JANUARY 1991 – REVISED NOVEMBER 2002

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$			SN54ABT245A		SN74ABT245B		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1	2	3.2	0.8	3.8	1	3.6	ns
t_{PHL}			1	2.6	3.5	1	4.2	1	3.9	
t_{PZH}	$\overline{OE}$	A or B	2	3.5	4.5	1.2	6.2	2	5.6	ns
t_{PZL}			1.9	4	5.3	1.3	6.8	1.9	6.2	
t_{PHZ}	$\overline{OE}$	A or B	2.2	4.4	5.4	2.2	6.1	2.2	5.9	ns
t_{PLZ}			1.5	3	4	1.0	4.9	1.5	4.5	
$t_{sk(o)}$					0.5				0.5	ns



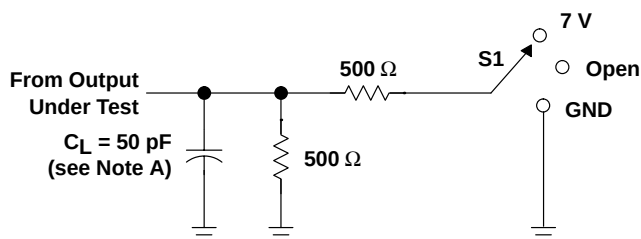
SN54ABT245A, SN74ABT245B

OCTAL BUS TRANSCEIVERS

WITH 3-STATE OUTPUTS

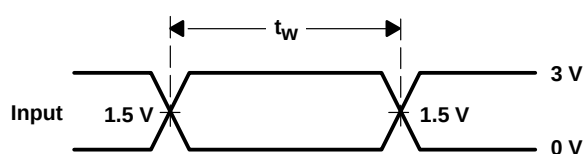
SCBS081J – JANUARY 1991 – REVISED NOVEMBER 2002

PARAMETER MEASUREMENT INFORMATION

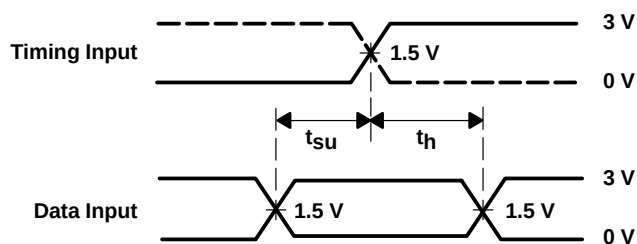


LOAD CIRCUIT

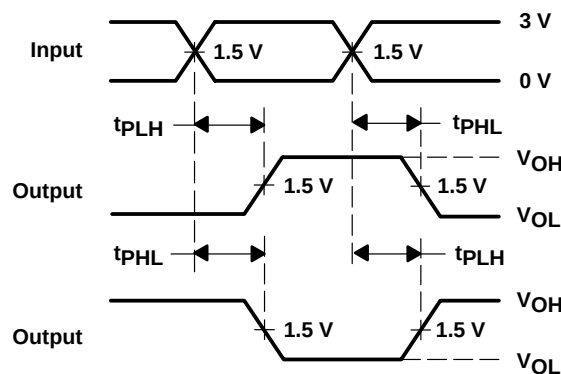
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



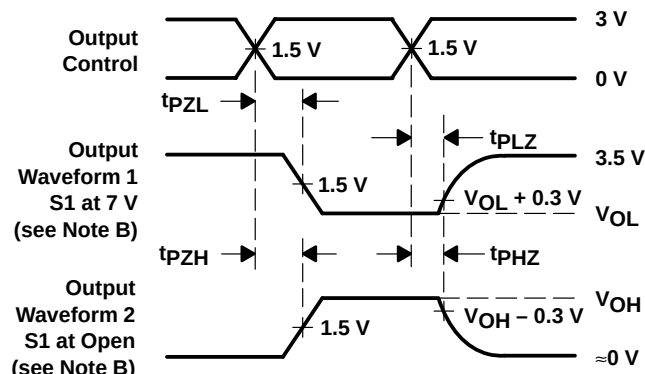
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

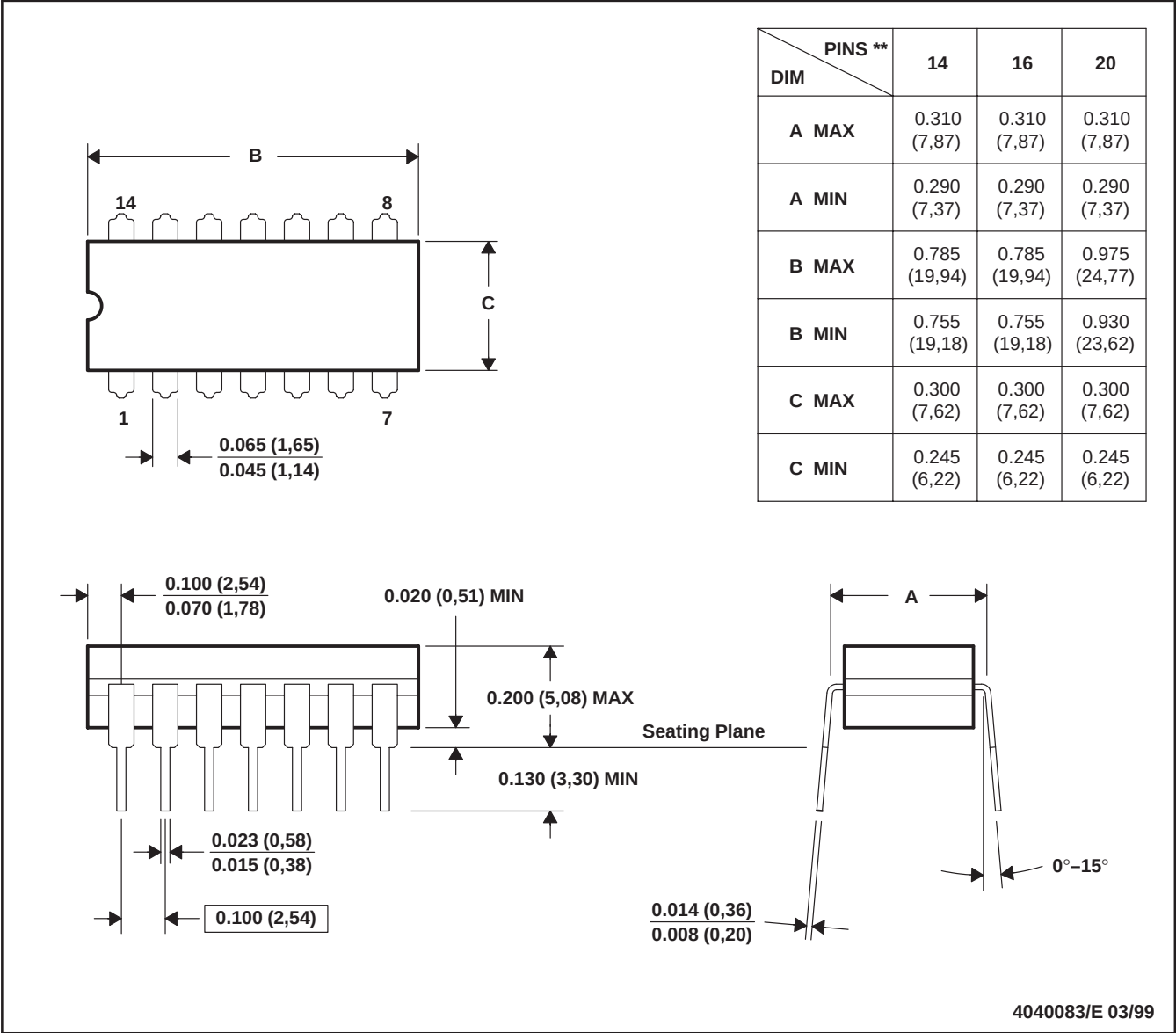
- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

J (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

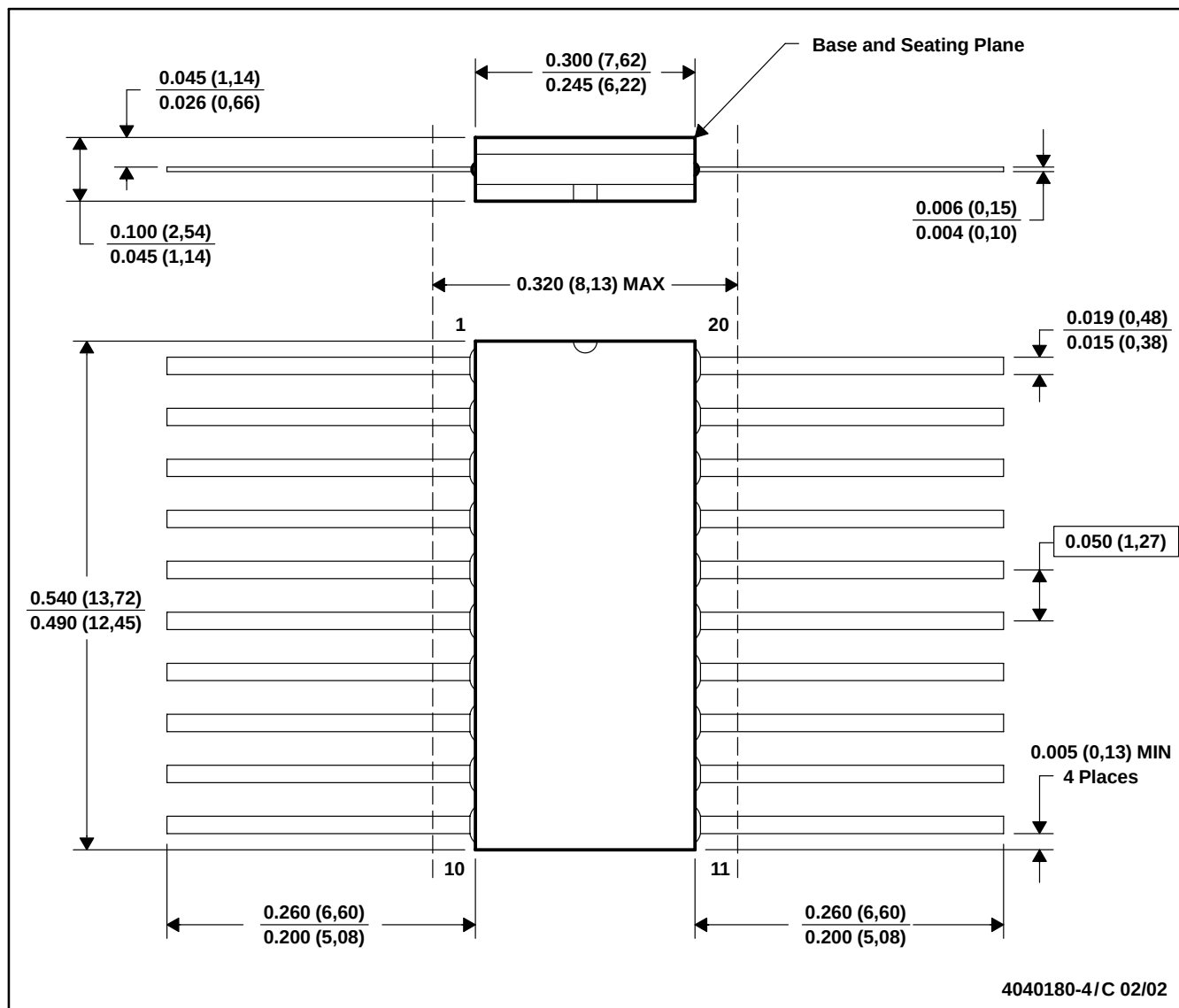
14 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, and GDIP1-T20

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

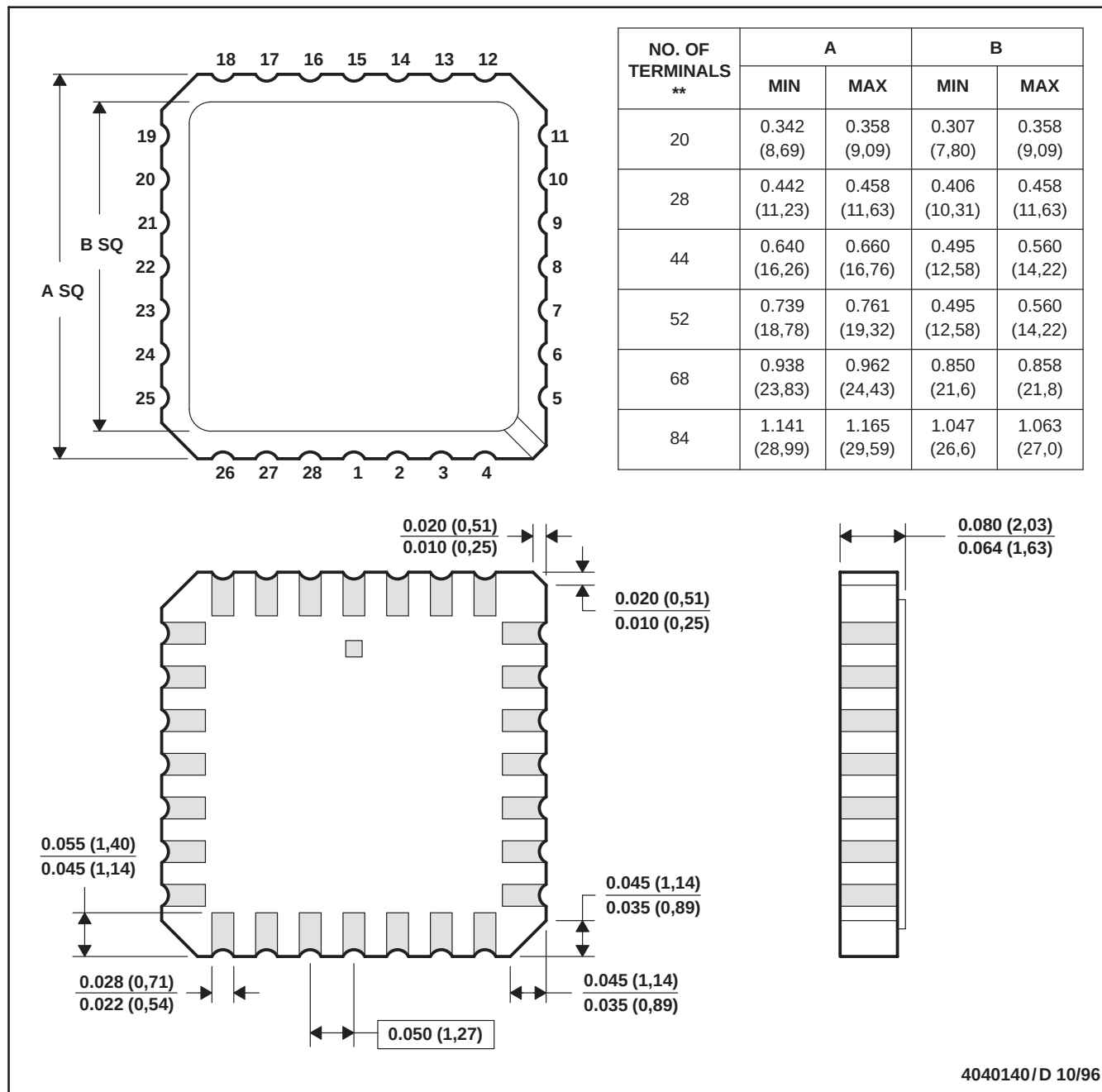


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

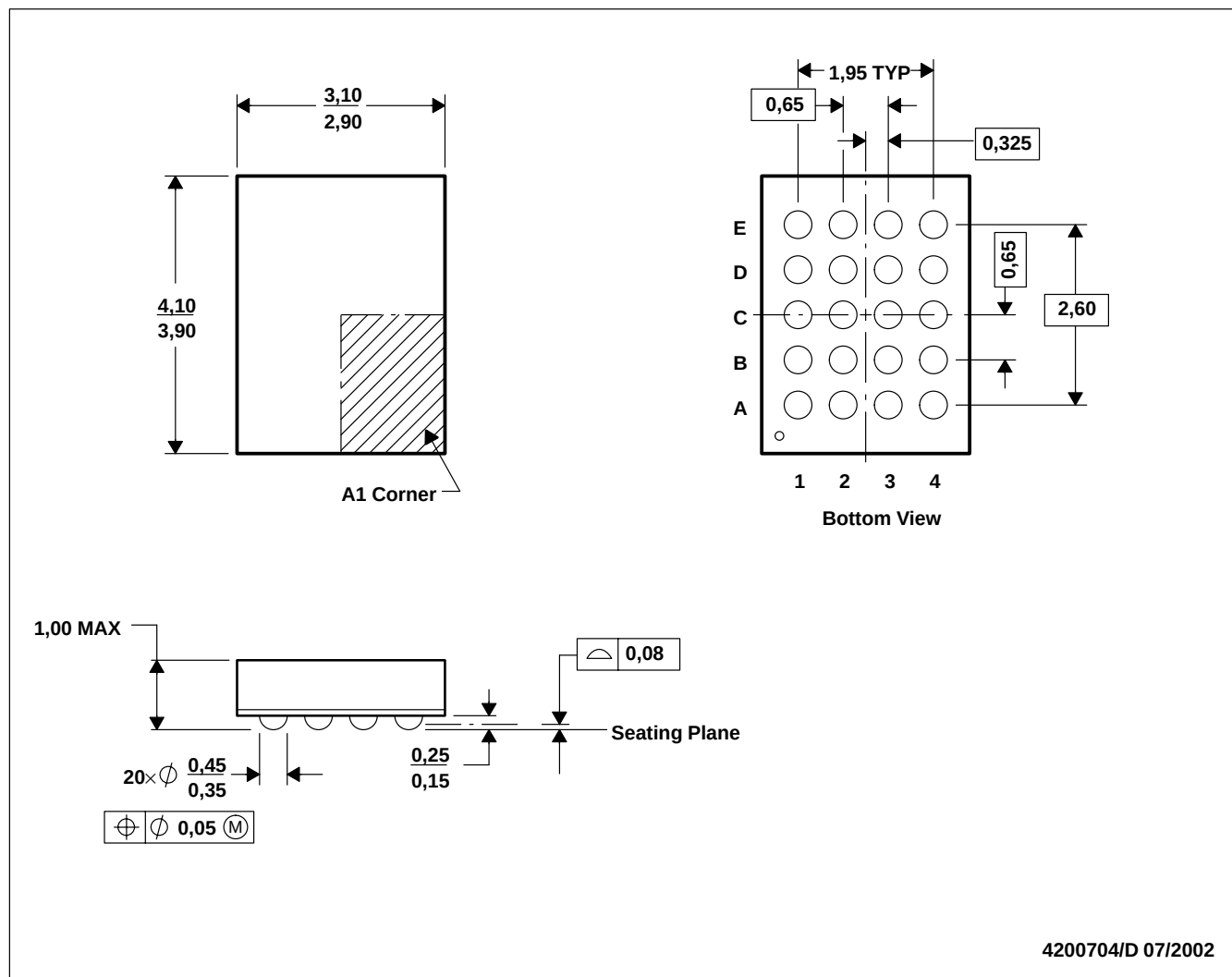
28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. MicroStar Junior™ configuration
 - D. Falls within JEDEC MO-225 variation BC.
 - E. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

MicroStar Junior is a trademark of Texas Instruments.

PLASTIC DUAL-IN-LINE PACKAGE

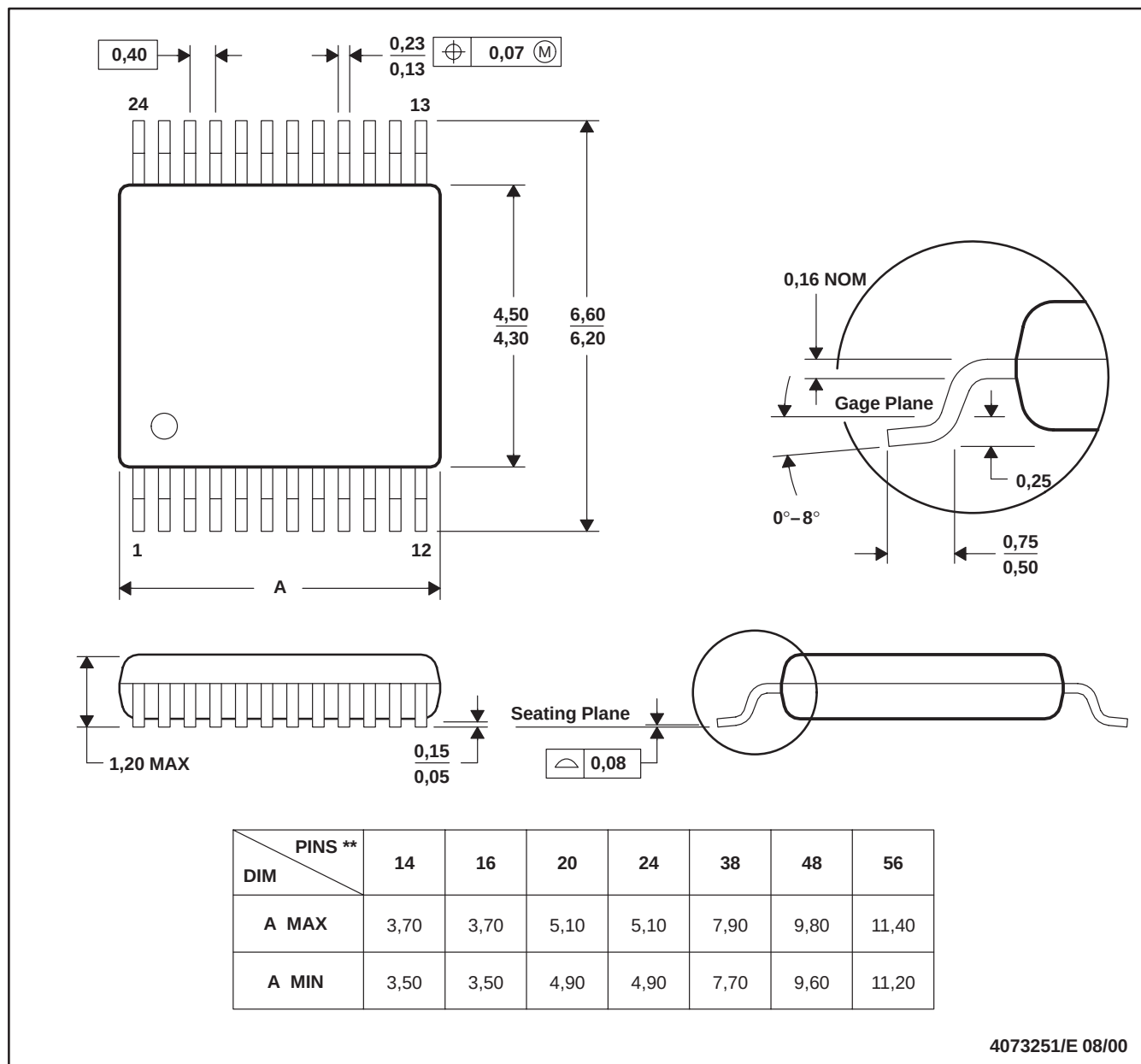
4040049/E 12/2002

 D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

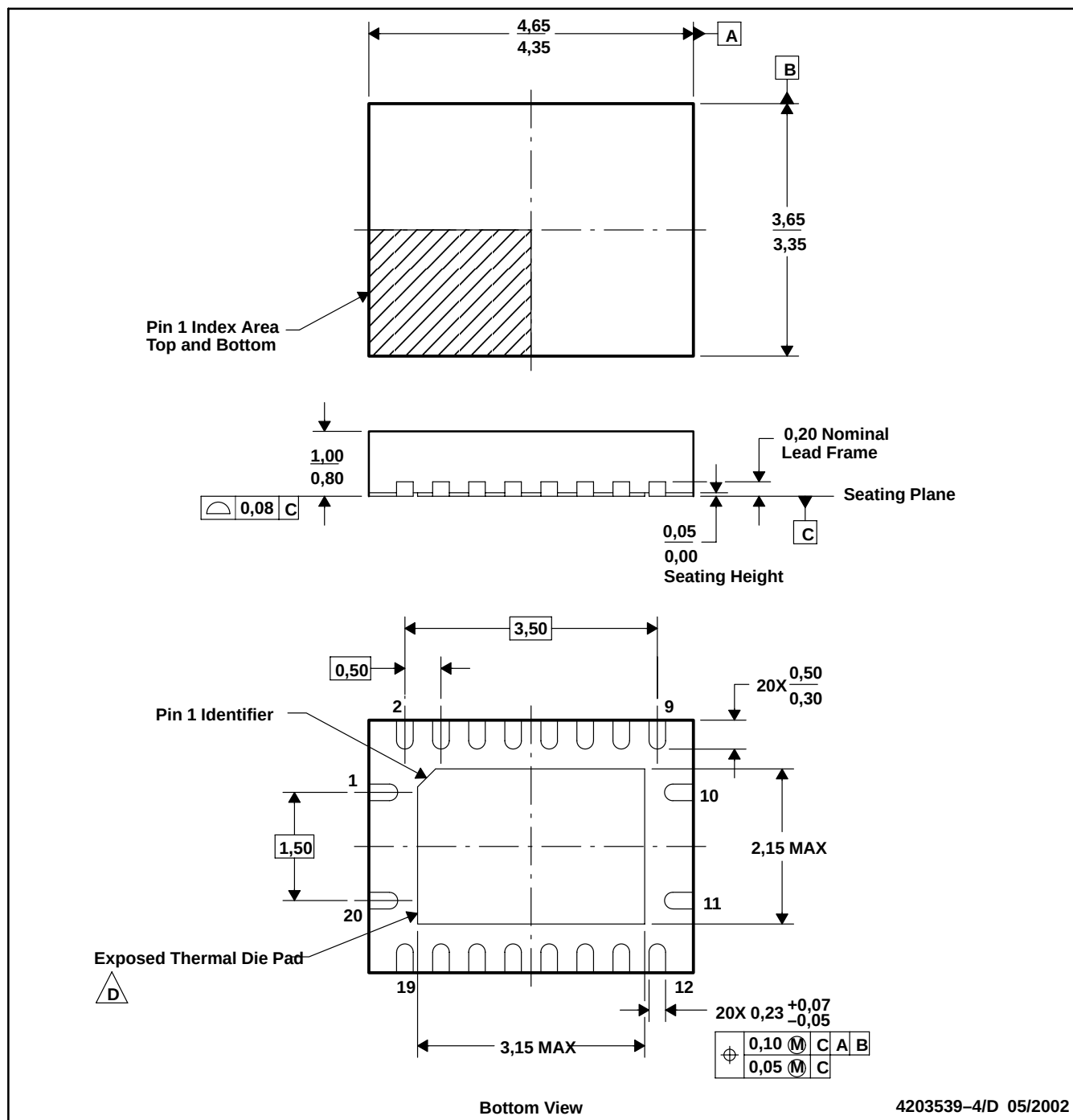
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

RGY (S-PQFP-N20)

PLASTIC QUAD FLATPACK

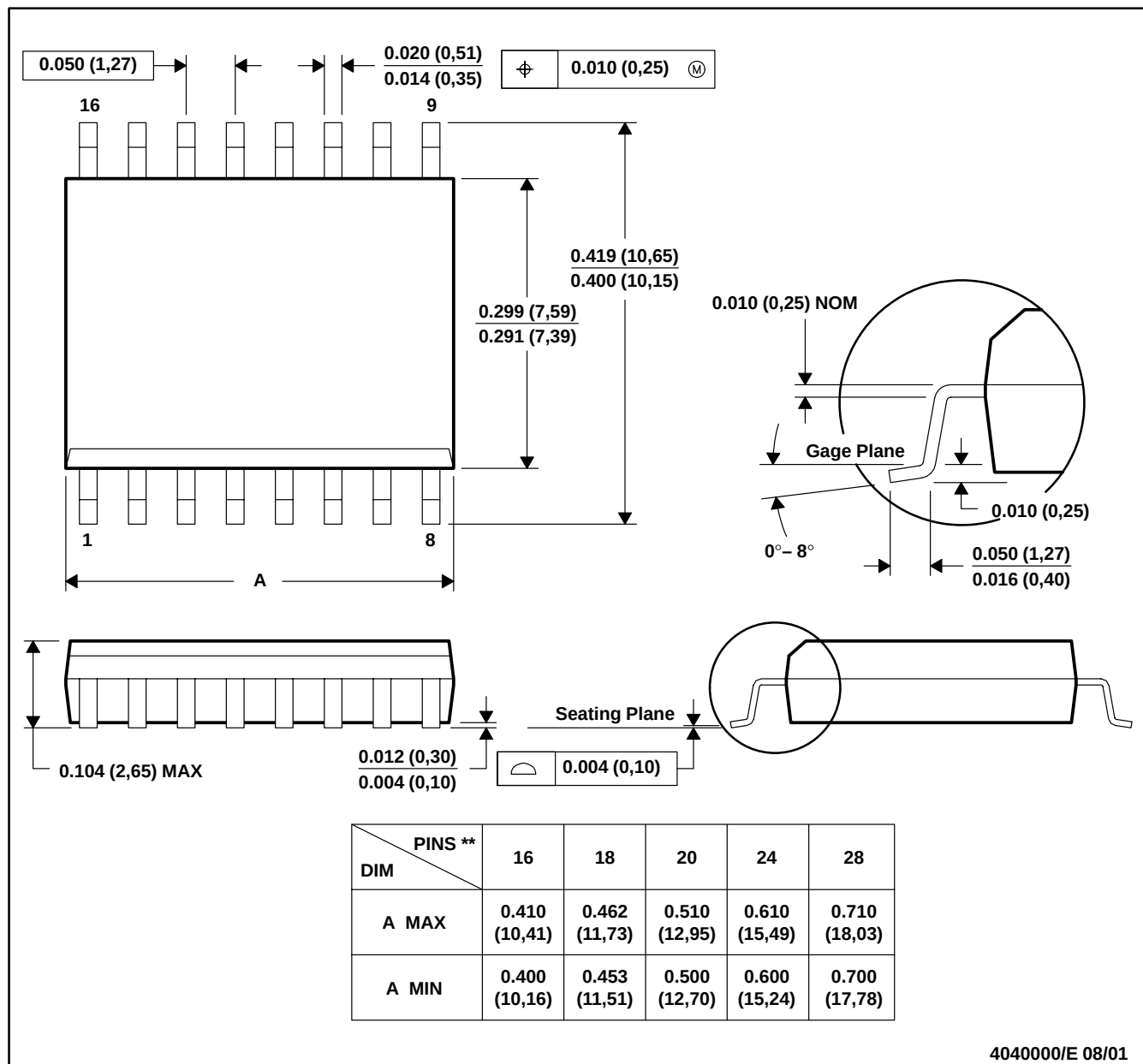


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) Package configuration.
 - D. The Package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN

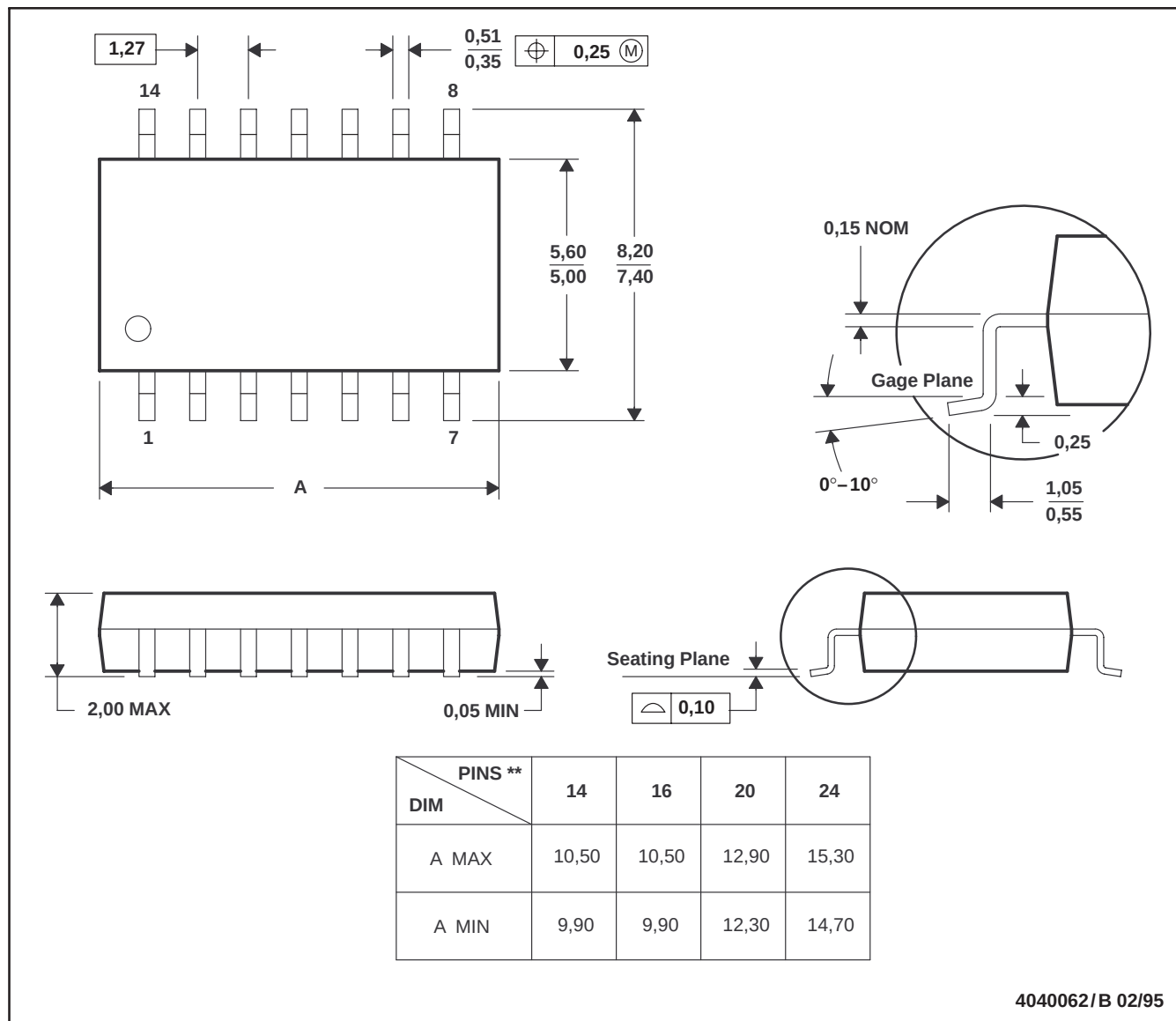


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-013

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN

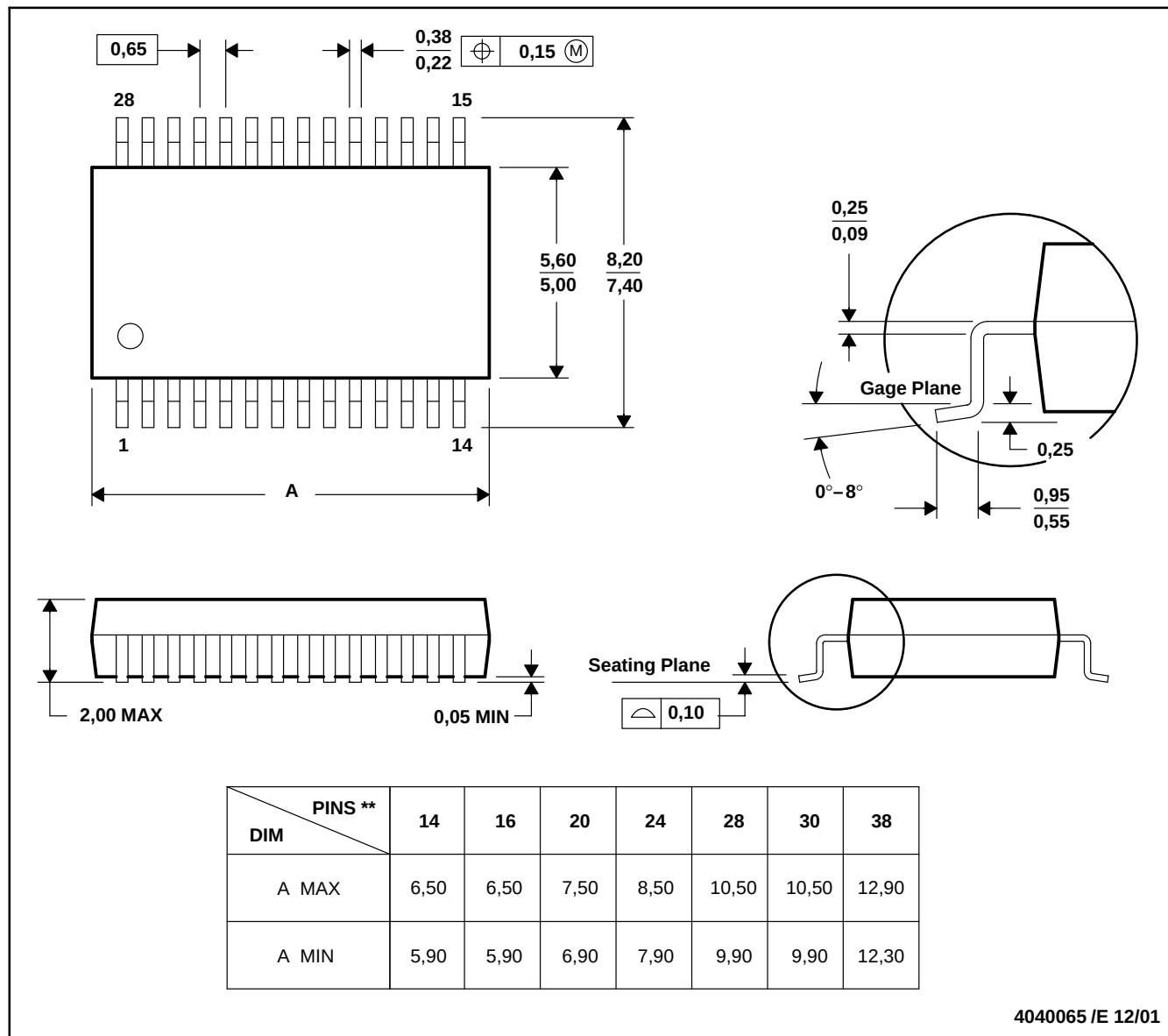


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN

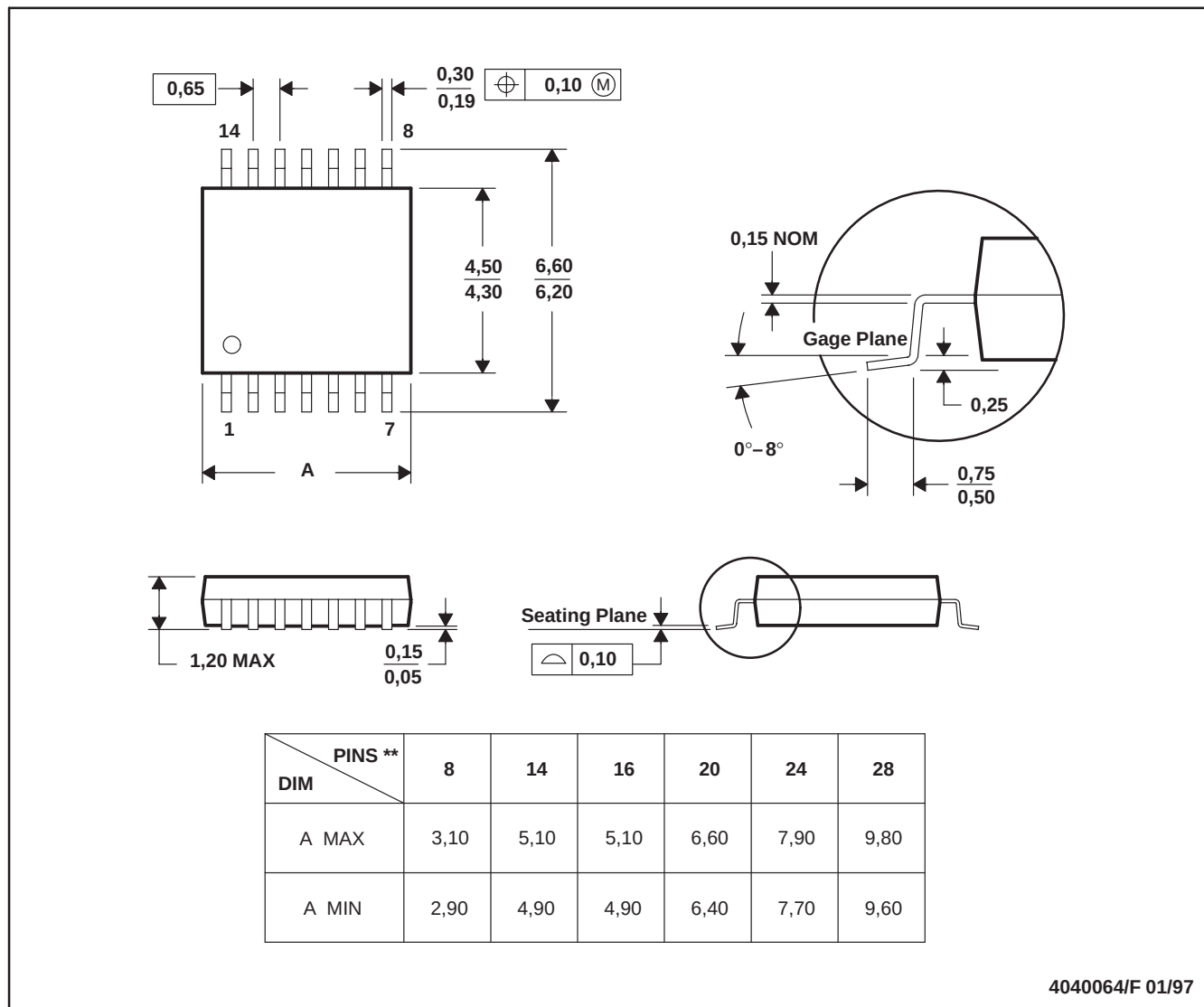


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265